

SOT1317-1

HTFLGA80, plastic thermal enhanced thin fine-pitch land grid array package; 80 terminals; resin based; 12 mm x 12 mm x 1.1 mm body

2 July 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HTFLGA80
Package type industry code	HTFLGA80
Package style descriptive code	LGA (land grid array package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	28-06-2021
Manufacturer package code	SOT1317

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	11.9	12	12.1	mm
package width	11.9	12	12.1	mm
seated height	1.05	1.1	1.2	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	80	-	



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2 Package outline

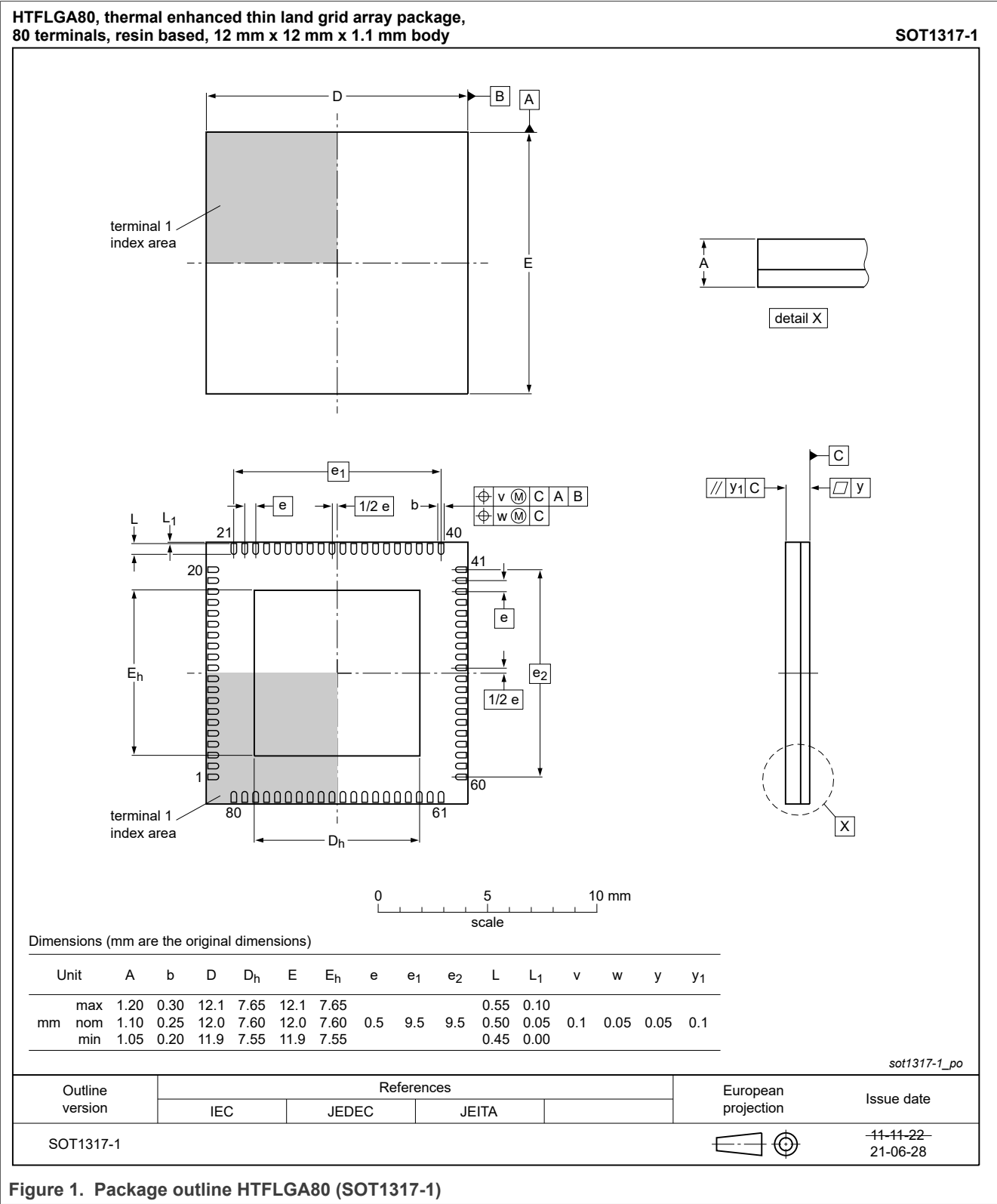


Figure 1. Package outline HTFLGA80 (SOT1317-1)

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3 Legal information

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